

ELM37401FA-VB Datasheet

P-Channel 20 V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A) ^c	Q _g (Typ.)			
- 20	0.080 at V _{GS} = - 4.5 V	- 3.1	4.3 nC			
	0.100 at V _{GS} = - 2.5 V	- 2.3	4.5110			

FEATURES

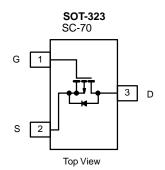
- Halogen-free According to IEC 61249-2-21 **Definition**
- Trench Power MOSFET 100 % R_g Tested
- Compliant to RoHS Directive 2002/95/EC

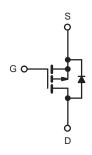


HALOGEN FREE

APPLICATIONS

- Load Switch
- DC/DC Converters





P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T	$_{A}$ = 25 °C, unless oth	erwise noted)		
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	- 20	V	
Gate-Source Voltage		V _{GS}	± 12	
	T _C = 25 °C		- 3.1	
Continuous Drain Current (T, = 150 °C)	T _C = 70 °C		- 2.1	
Continuous Diairi Current (1) = 130 °C)	T _A = 25 °C	I _D	- 1.4 ^{a, b}	
	T _A = 70 °C		- 1.1 ^{a, b}	А
Pulsed Drain Current	I _{DM}	- 6		
Ocationary Oceana Basis Biodo Oceana	T _C = 25 °C	L	- 0.4	
Continuous Source-Drain Diode Current	T _A = 25 °C	ls —	- 0.3	
	T _C = 25 °C		0.5	
Manianum Pauran Disaination	T _C = 70 °C		0.3	10/
Maximum Power Dissipation	T _A = 25 °C	P _D	0.4 ^{a, b}	W
	T _A = 70 °C		0.3 ^{a, b}	
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 50 to 150	°C	
Soldering Recommendations (Peak Temperature)		260		

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 10 s.
- c. Based on T_C = 25 °C.



THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient ^{a, b}	t ≤ 10 s	R _{thJA}	250	300	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	225	270	C/VV		

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. Maximum under steady state conditions is 360 °C/W.

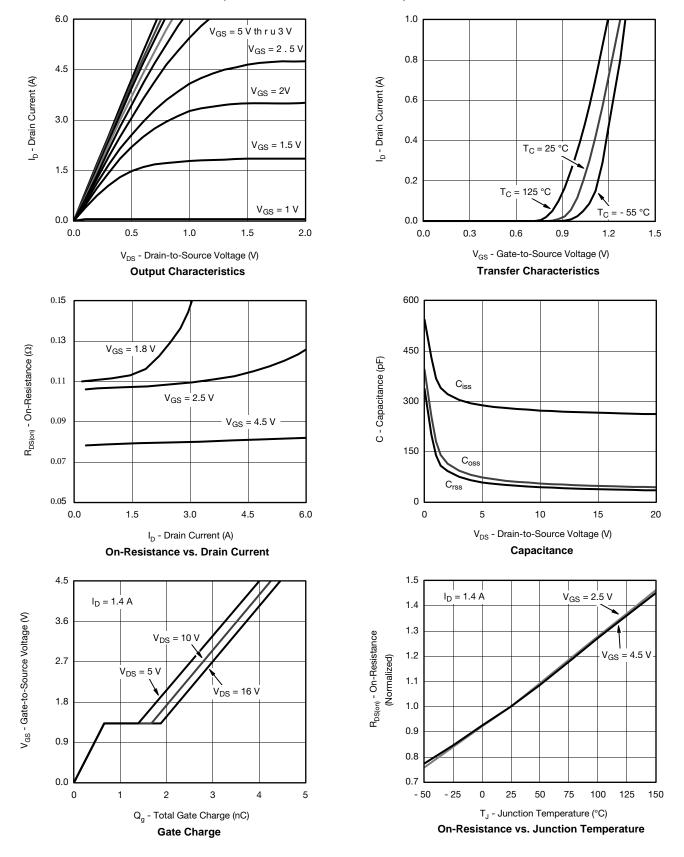
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$	- 20			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = - 250 μA		- 14		mV/°C
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = - 250 μA		2.4		
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 0.45		- 1.5	V
Gate-Source Leakage	I_{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}$			- 1	μA
Zeio Gate voltage Diain Current		$V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$			- 10	μΑ
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	- 2			Α
		$V_{GS} = -4.5 \text{ V}, I_D = -1.4 \text{ A}$		0.080		
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = -2.5 \text{ V}, I_D = -1.2 \text{ A}$		0.100		Ω
		V _{GS} = - 1.8 V, I _D = - 0.3 A		0.140		
Forward Transconductance ^a	9 _{fs}	$V_{DS} = -5 \text{ V}, I_{D} = -1.4 \text{ A}$		5		S
Dynamic ^b						
Input Capacitance	C _{iss}			272		
Output Capacitance	C _{oss}	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		55		pF
Reverse Transfer Capacitance	C _{rss}			44		-
Total Gate Charge	Qg	$V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -1.4 \text{ A}$		4.3	6.5	nC
				2.7	4.1	
Gate-Source Charge	Q_{gs} $V_{DS} = -10 \text{ V}, V_{GS} = -2.5 \text{ V}, I_D = -1.4 \text{ A}$			0.7		110
Gate-Drain Charge	Q_{gd}			1.0		
Gate Resistance	R_g	f = 1 MHz	1.4	7	14	Ω
Turn-On Delay Time	t _{d(on)}			12	20	
Rise Time	t _r	V_{DD} = - 10 V, R_L = 9.1 Ω		20	30	
Turn-Off DelayTime	t _{d(off)}	$I_D \cong$ - 1.1 A, V_{GEN} = - 4.5 V, R_g = 1 Ω		23	35	
Fall Time	t _f			9	18	ns
Turn-On Delay Time	t _{d(on)}			5	10	115
Rise Time	t _r	V_{DD} = - 10 V, R_L = 9.1 Ω		10	20	
Turn-Off DelayTime	t _{d(off)}	$I_D \cong$ - 1.1 A, V_{GEN} = - 8 V, R_g = 1 Ω		18	27	
Fall Time	t _f			7	14	1
Drain-Source Body Diode Characterist	ics					
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			- 2.4	Α
Pulse Diode Forward Current ^a	I _{SM}				- 6	_ ^
Body Diode Voltage	V _{SD}	I _F = - 0.7 A		- 0.8	- 1.2	V
Body Diode Reverse Recovery Time	t _{rr}			18	27	ns
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = - 0.7 A, dl/dt = 100 A/μs, T _{.I} = 25 °C		7	14	nC
Reverse Recovery Fall Time	t _a	1F = -0.7 A, αι/αι = 100 A/μS, 1J = 25 °C		7		ne
Reverse Recovery Rise Time	t _h	t _b		11		ns

Notes:

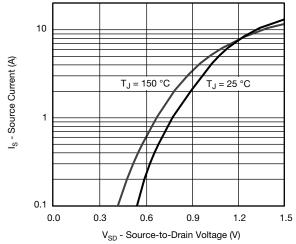
- a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

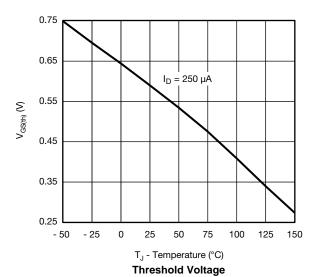


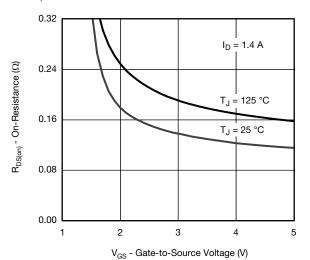




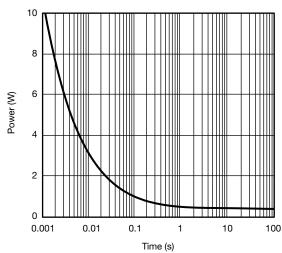


Source-Drain Diode Forward Voltage

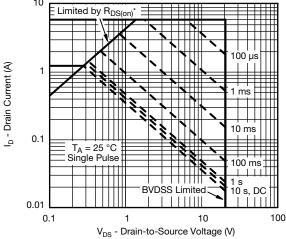




On-Resistance vs. Gate-to-Source Voltage



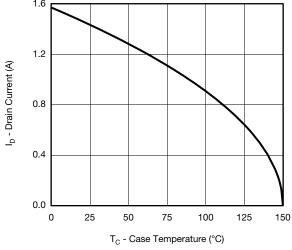
Single Pulse Power, Junction-to-Ambient



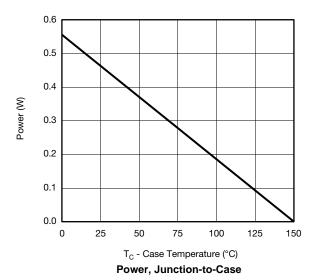
* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

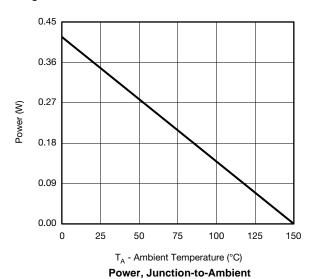
Safe Operating Area, Junction-to-Ambient





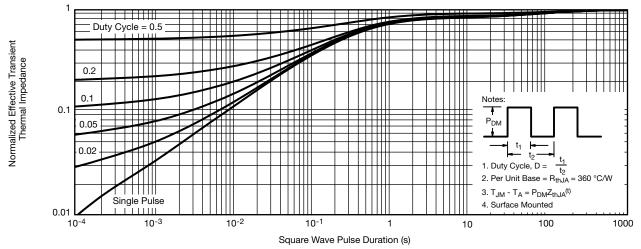
Current Derating*



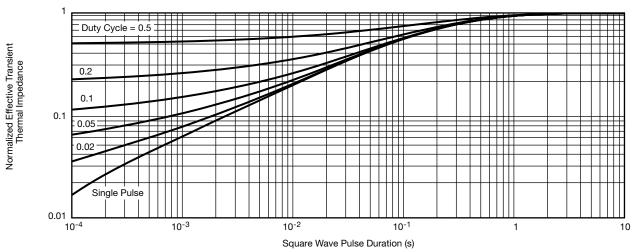


* The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





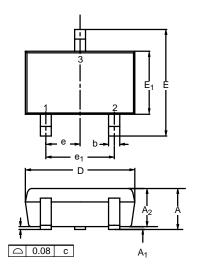
Normalized Thermal Transient Impedance, Junction-to-Ambient

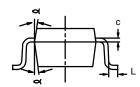


Normalized Thermal Transient Impedance, Junction-to-Foot



SC-70: 3-LEADS

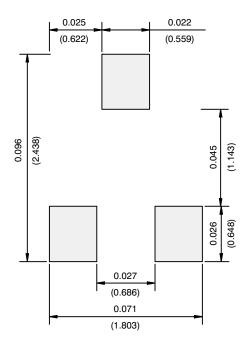




	MILLIMETERS INCHES				S	
Dim	Min	Nom	Max	Min	Nom	Max
Α	0.90	-	1.10	0.035	-	0.043
A ₁	_	-	0.10	_	_	0.004
A ₂	0.80	-	1.00	0.031	_	0.039
b	0.25	-	0.40	0.010	_	0.016
С	0.10	-	0.25	0.004	-	0.010
D	1.80	2.00	2.20	0.071	0.079	0.087
Е	1.80	2.10	2.40	0.071	0.083	0.094
E ₁	1.15	1.25	1.35	0.045	0.049	0.053
е	0.65BSC				0.026BSC	;
e ₁	1.20	1.30	1.40	0.047	0.051	0.055
L	0.10	0.20	0.30	0.004	0.008	0.012
۵	7°Nom			7°Nom		
ECN: S-03946—Rev. C, 09-Jul-01 DWG: 5549						



RECOMMENDED MINIMUM PADS FOR SC-70: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)



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